



PATENT
8013-1147

IN THE U.S. PATENT AND TRADEMARK OFFICE

In re application of:

Hirokazu HONDA

Confirmation No. 7187

Serial No. 09/678,609

GROUP 2827

Filed October 4, 2000

Examiner David E. Graybill

MULTILAYER INTERCONNECTION BOARD, SEMICONDUCTOR
DEVICE HAVING THE SAME, AND METHOD OF FORMING
THE SAME AS WELL AS METHOD OF MOUNTING THE
SEMICONDUCTOR CHIP ON THE INTERCONNECTION BOARD

AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

May 11, 2004

Sir:

In response to the Official Action of December 16,
2003, please amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing
of claims that begins on page 2 of this paper.

Remarks begin on page 14 of this paper.